



Pulsar Solderability Testing



The Hentec Pulsar Solderability Test System is offered in single or dual pot configurations. The Pulsar uses a “dip and look” method and can be configured for low-volume lead tinning production. Designed for lab environments, the table-top system provides high precision PLC motion control, easy touch screen programming, and PID temperature management for complete process control. Hentec’s rapid custom tool holder fabrication can solve any odd-form or exotic component handling challenges.

Pulsar Solderability Test System

Dip and Look Method

Solder Management

Temp Control	0-325°C +/- 5°C Max PI proportional
Standard Process Area	(W x L x H) 4 x 6 x 2.5”
Capacity	15 lbs 6.8 kgs
Dross Wiper	Included
Flux Process Area	(W x L x H) 3.5 x 3.5 x 1”

Operation

Configuration	Single Pot Dual Pot (optional)
Programming	16 Program capacity
Process Control	2.5” at .01” Resolution Process rate at .04-2.0” per sec adjustable

Physical

Dimensions	(L x W x H) 30 x 22 x 19”
Electrical	110 VAC 1Ø 60 hz 15 amp
Construction	Stainless steel wet surfaces Epoxy coated external surfaces
Solder Type	Lead or Lead Free compatible
Industry Standards	J-STD-002, J-STD-003, MIL-STD-202 Method 208
Compliance	Meets CE, UL, and NRTL standards

